



# 30V P-Channel MOSFETs

## General Description

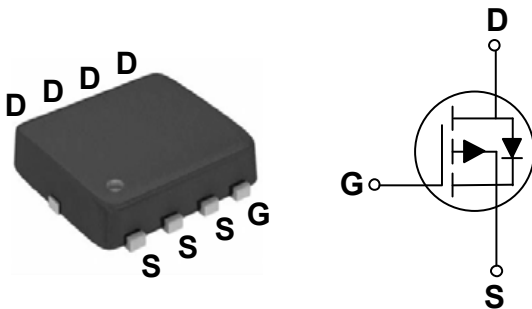
These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

$BV_{DSS}$	$R_{DS(ON)}$	$I_D$
-30 V	29 mΩ	-21 A

## Features

- $R_{DS(ON)} \leq 29m\Omega @ V_{GS} = -10V$
- Fast Switching
- Green Device Available

PPAK3X3 Pin Configuration



## Applications

- Notebook
- Battery Protection
- Load Switch
- Hand-Held Instruments

## Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-30	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Drain Current - Continuous	-21	A
$I_{DM}$	Drain Current - Pulsed (NOTE 1)	-90	A
$P_D$	Power Dissipation ( $T_A=25^\circ C$ )	2	W
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
Marking Code		PC029	

## Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	---	62	$^\circ C/W$



Electrical Characteristics (T<sub>J</sub>=25°C, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> = -250uA	-30	---	---	V
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> = -24V, V <sub>GS</sub> =0V	---	---	-1	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> = ±20V, V <sub>DS</sub> =0V	---	---	±100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = -10V, I <sub>D</sub> = -4A	---	---	29	mΩ
		V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -2A	---	---	50	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> = -250uA	-1	---	-2.5	V
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> = -5V, I <sub>D</sub> = -7A	---	10	---	S

Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> = -20V, V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -7A	---	9.5	---	nC
Q <sub>gs</sub>	Gate-Source Charge		---	3.64	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	4	---	
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DS</sub> = -24V, V <sub>GS</sub> = -10V, R <sub>G</sub> = 3.3Ω, I <sub>D</sub> = -1A	---	6.2	---	nS
T <sub>r</sub>	Rise Time		---	2.6	---	
T <sub>d(off)</sub>	Turn-Off Delay Time		---	30.9	---	
T <sub>f</sub>	Fall Time		---	20.8	---	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = -15V, V <sub>GS</sub> =0V, F=1MHz	---	945	---	pF
C <sub>oss</sub>	Output Capacitance		---	105	---	
C <sub>riss</sub>	Reverse Transfer Capacitance		---	68.5	---	
R <sub>g</sub>	Gate Resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, F=1MHz	---	8	---	Ω

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> = 0V, I <sub>S</sub> = -2.3A	---	---	-1.2	V

NOTES :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
3. Essentially independent of operating temperature.



Characteristics Curves

FIG. 1-Normalized  $V_{GS(th)}$  vs.  $T_J$

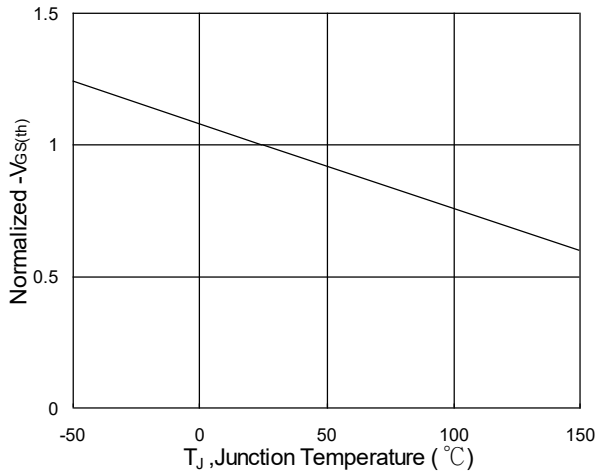


FIG. 2-Normalized  $R_{DS(on)}$  vs.  $T_J$

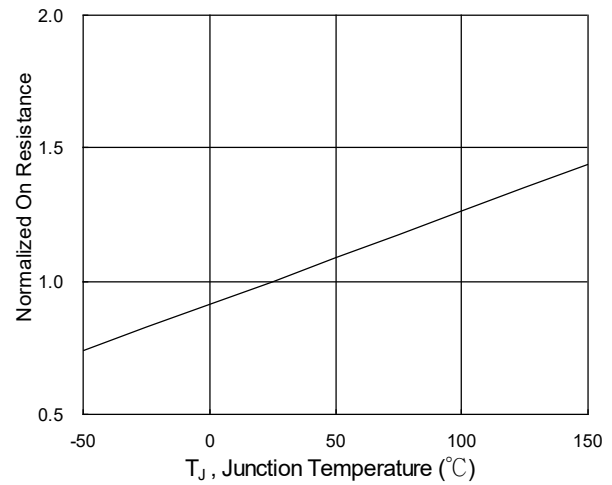


FIG. 3-Source-Drain Diode Forward

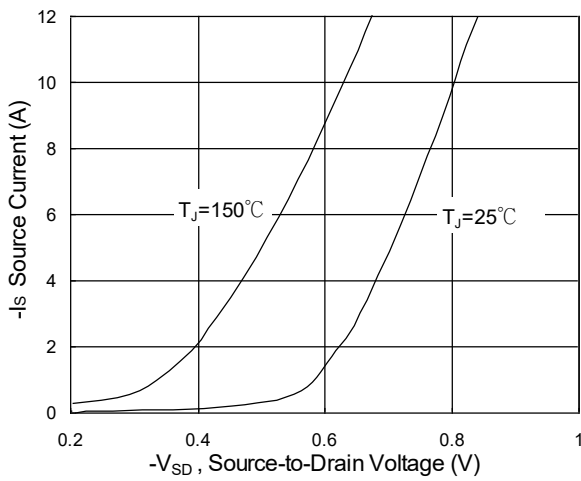


FIG. 4-Gate Charge Characteristics

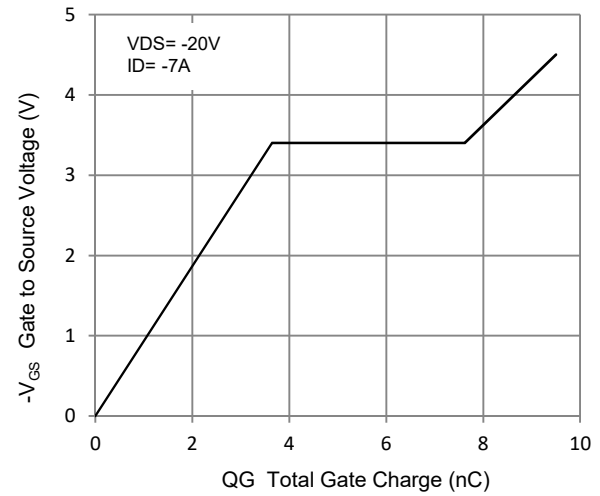


Fig. 5-Capacitance

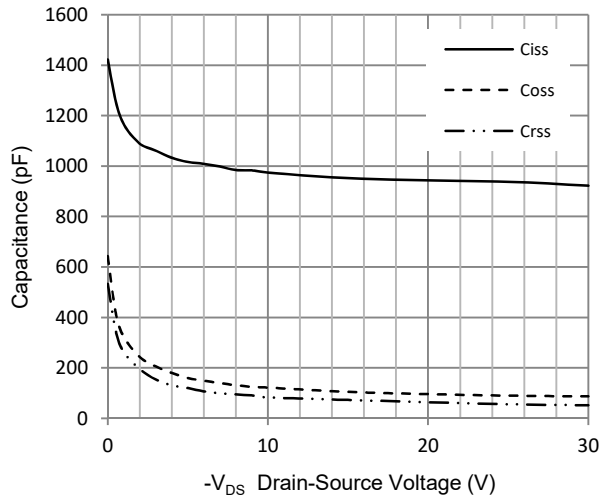
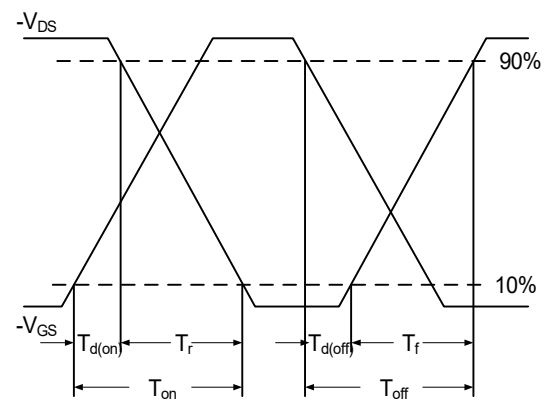
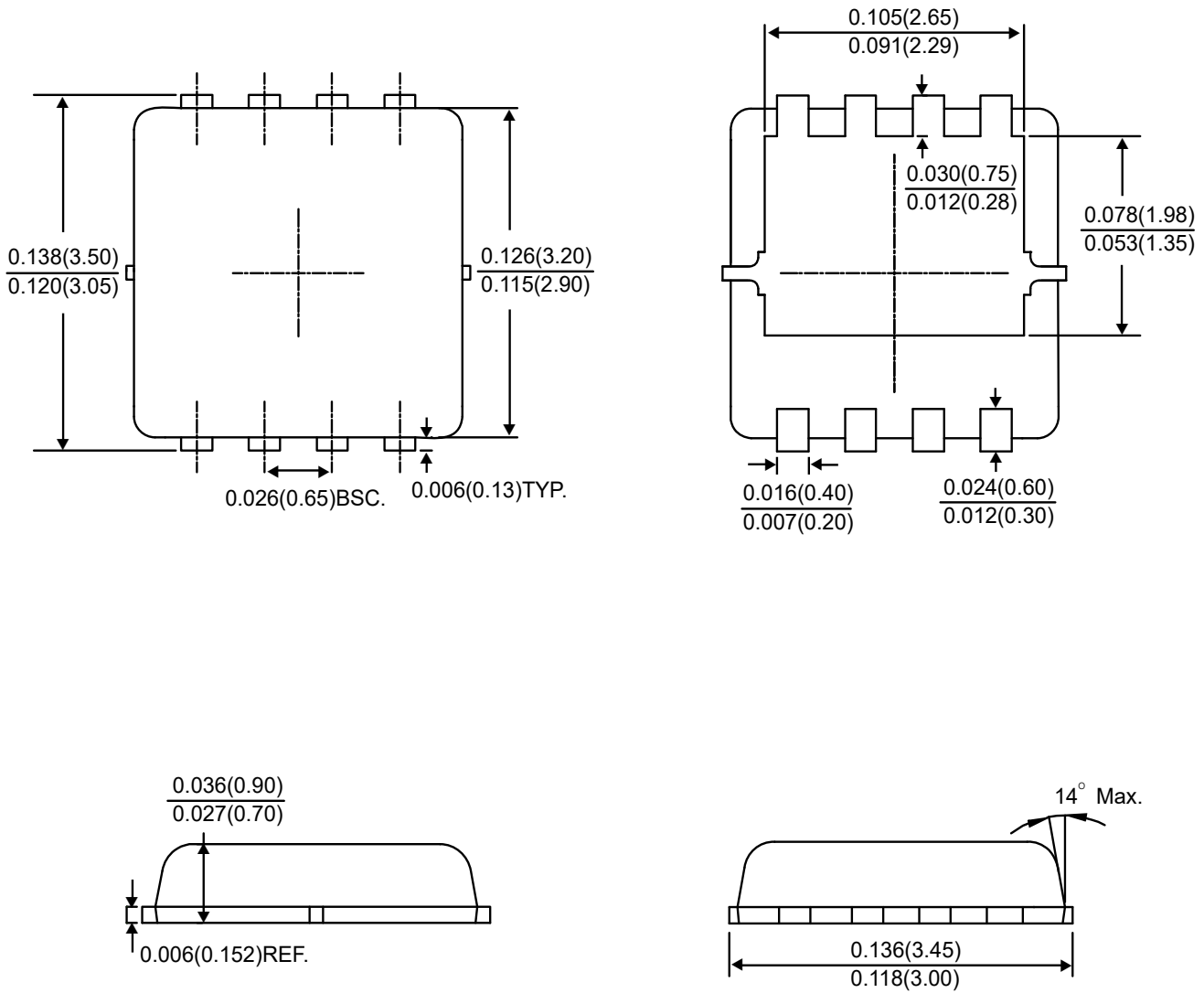


Fig. 6-Switching Time Waveform





Package Outline Dimensions



PPAK3X3

Dimensions in inches and (millimeters)



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